

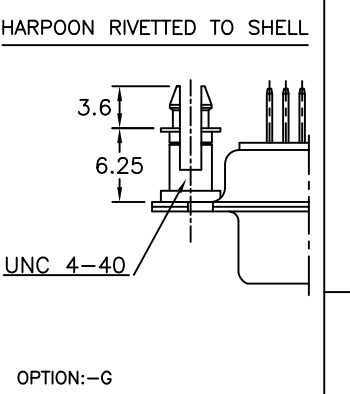
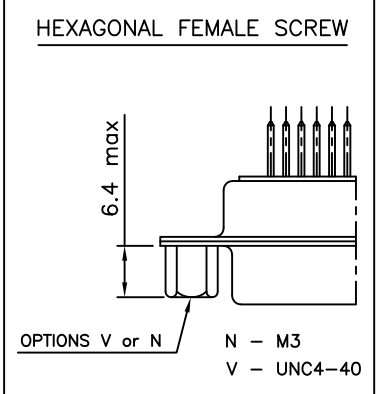
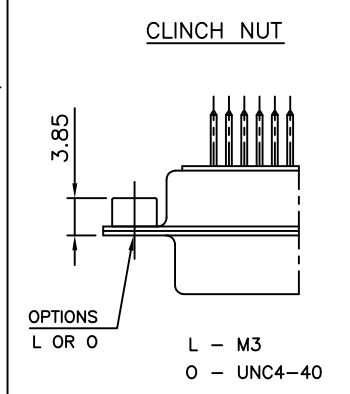
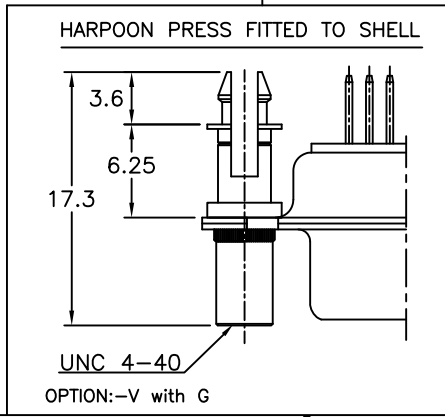
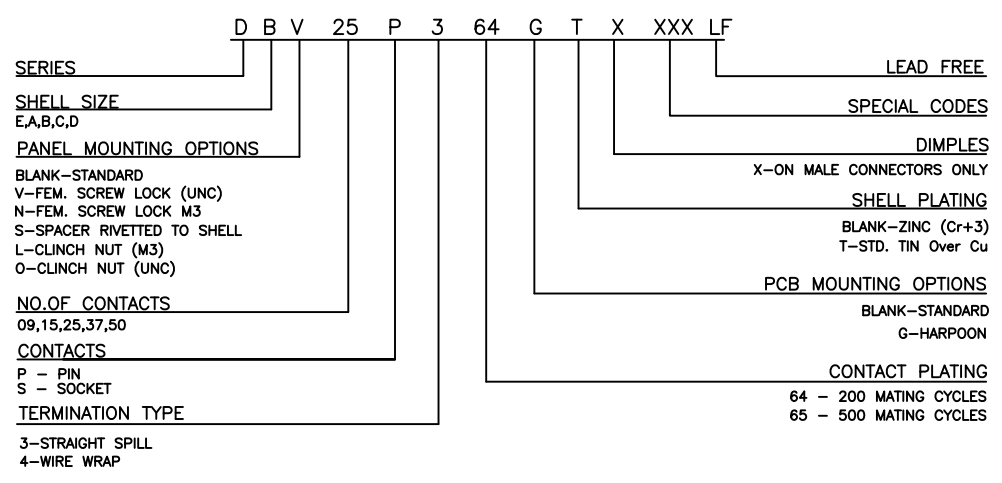
50	P	66.65	52.68	61.11	11.08	14.99	11.09	5.85	55.07	13.31	1.50	1.0
	S	66.65	52.30	61.11	10.62	14.99	11.21	6.05	55.07	13.31	1.10	0.8
37	P	68.94	55.30	63.50	8.23	12.17	11.09	5.85	57.45	10.46	1.50	1.0
	S	68.94	54.71	63.50	7.77	12.17	11.21	6.05	57.45	10.46	1.10	0.8
25	P	52.65	38.84	47.04	8.23	12.17	11.07	5.85	41.02	10.46	1.10	0.8
	S	52.65	38.25	47.04	7.77	12.17	11.21	6.05	41.02	10.46	1.10	0.8
15	P	38.76	25.12	33.32	8.23	12.17	10.99	5.85	27.25	10.46	1.10	0.8
	S	38.76	24.54	33.32	7.77	12.17	11.21	6.05	27.25	10.46	1.10	0.8
09	P	30.43	16.79	24.99	8.23	12.17	10.99	5.85	19.02	10.46	1.10	0.8
	S	30.43	16.21	24.99	7.77	12.17	11.21	6.05	19.02	10.46	1.10	0.8
SHELL SIZE		A <sup>+0.76</sup>	B <sup>+0.25</sup>	C <sup>+0.12</sup>	D <sup>+0.25</sup>	E <sup>+0.76</sup>	F <sup>MAX</sup>	G <sup>+0.15</sup>	H <sup>+0.51</sup>	J <sup>+0.51</sup>	K <sup>±0.2</sup>	L <sup>+0.22</sup>

NOTE: INSIDE DIMENSION OF MALE AND OUTSIDE DIMENSION OF THE FEMALE CONNETOR

TECHNICAL SPECIFICATIONS

- SHELLS : TIN/ZINC PLATED STEEL
- CONTACTS DIA ON ACTIVE AREA : Ø1 MM.
- CONTACTS MATERIAL : COPPER ALLOY
- CONTACT PLATING : GXT / GOLD OVER NICKEL (ACTIVE ZONE)  
TIN OVER NICKEL (TERMINATION ZONE)
- FOR LEAD FREE PLATING : 2µ MIN. TIN TOP OVER  
1.27µ MIN. NICKEL UNDER PLATE (ON TERMINATION ZONE)
- INSULATOR MATERIAL : SELF EXTINGUISHING THERMOPLASTIC-  
TO UL CLASS 94 V0  
THE HOUSING WILL WITHSTAND EXPOSURE TO 260-265°C  
IF WE USE PROTECTIVE ADHESIVE (type Kapton or Teflon)  
OR PROTECTIVE METALLIC DEVICE
- OPERATING TEMPERATURE : -55°C +125°C
- OPERATING CURRENT : 5 A PER CONTACT
- CONTACT RESISTANCE : ≤10m Ω
- INSULATION RESISTANCE : >5000 M Ω
- MAXIMUM VOLTAGE : 1000 V.r.m.s
- MECHANICAL ENDURANCE : 500 MATINGS FOR CODE 64  
200 MATINGS FOR CODE 65
- DAMP HEAT : 56 DAYS FOR ≥0.75µ GOLD PLATING  
21 DAYS FOR <0.40µ GOLD PLATING

ORDERING INFORMATION



mat'l. code SEE NOTE 4		surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection MM		product family							
D 106-0074 GJV 2006/06/08		E 109-0179 AMR 2009/09/04		F 109-0195 AMR 2009/09/04		G 111-0003 AMR 2011/01/06 dr Mini K Vandanath 1999/03/20		H 111-0047 AMR 2011/03/05 engr George V Joseph 1999/03/20		I 111-0047 AMR 2011/03/05 chr Abhilash M R 2009/09/04		J 111-0047 AMR 2011/03/05 appd Sudhir Varma 2009/09/04		K 111-0047 AMR 2011/03/05	
sheet index		revision sheet		H 1											

"This LF product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 3.5 seconds in a wave solder application with a 1.6mm minimum thick circuit board.

Packaging as per GS-14-920

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